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Method for achieving a wear performance which is as linear as possible and tool having a wear performance which is as linear as possible

Abstract

The invention relates to the material-removing machining of wafer-like workpieces, in particular semiconductor wafers. The subject matter of the invention is a method for achieving a wear performance which is as linear as possible in the case of a tool which has an essentially planar working surface for the material-removing machining of wafer-like workpieces, and a tool which has a wear performance which is as linear as possible. The subject matter of the invention is also a method and a device for measuring a wear profile on an essentially planar working surface for the material-removing machining of wafer-like workpieces. Finally, the subject matter of the invention is also a carrier which is used for the two-sided material-removing machining of wafer-like workpieces.

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